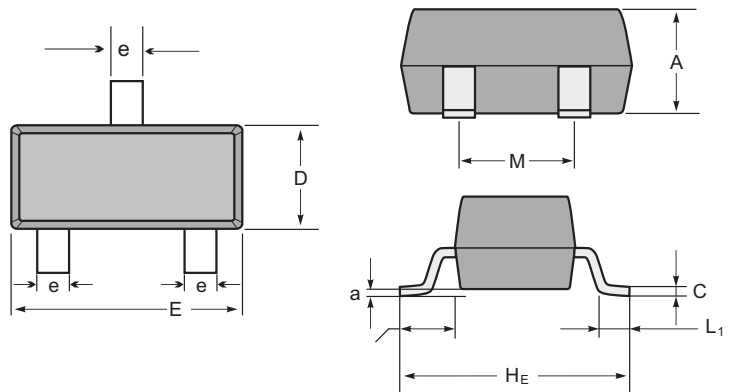
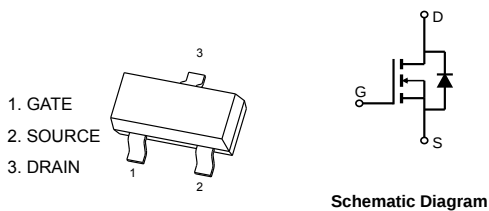


Features

- 20V, 2.3A
- $R_{DS(ON)} < 60m\Omega @ V_{GS} = 4.5V$
- $R_{DS(ON)} < 90m\Omega @ V_{GS} = 2.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free

Applications

- Load Switch
- PWM Application
- Power Management



SOT-23 mechanical data

UNIT		A	C	D	E	H _E	e	M	L	L ₁	a
mm	max	1.1	0.15	1.4	3.0	2.6	0.5	1.95	0.55 (ref)	0.36 (ref)	0.0
	min	0.9	0.08	1.2	2.8	2.2	0.3	1.7			0.15
mil	max	43	6	55	118	102	20	77	22 (ref)	14 (ref)	0.0
	min	35	3	47	110	87	12	67			6

Absolute Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Symbol	Parameter	Value	Units
V _{DS}	Drain-to-Source Voltage	20	V
V _{GS}	Gate-to-Source Voltage	±12	V
I _D	Continuous Drain Current	T _A = 25°C	A
		T _A = 100°C	
I _{DM}	Pulsed Drain Current ⁽¹⁾	12	A
P _D	Power Dissipation	T _A = 25°C	W
R _{θJA}	Thermal Resistance, Junction to Ambient ⁽²⁾	103	°C/W
T _J , T _{STG}	Junction & Storage Temperature Range	-55 to 150	°C

DMG2302UK

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 20V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±12V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	0.5		1.0	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 4.5V, I _D = 3A	-	45	60	mΩ
		V _{GS} = 2.5V, I _D = 2A	-	65	90	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 10V, f = 1MHz	-	200	-	pF
C _{oss}	Output Capacitance		-	35	-	pF
C _{rss}	Reverse Transfer Capacitance		-	28	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 4.5V V _{DD} = 10V, I _D = 2A	-	3	-	nC
Q _{gs}	Gate Source Charge		-	0.5	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	0.7	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = 4.5V, V _{DD} = 10V I _D = 2A, R _{GEN} = 3Ω	-	3	-	ns
t _r	Turn-On Rise Time		-	11	-	ns
t _{d(off)}	Turn-Off DelayTime		-	20	-	ns
t _f	Turn-Off Fall Time		-	8	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	3	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	12	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 3A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I _F = 2A, di/dt = 100A/us	-	4.3	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	0.6	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. $R_{\theta JA}$ is measured with the device mounted on a 1inch^2 pad of 2oz copper FR4 PCB
 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

RATING AND CHARACTERISTIC CURVES (DMG2302UK)

Figure 1: Output Characteristics

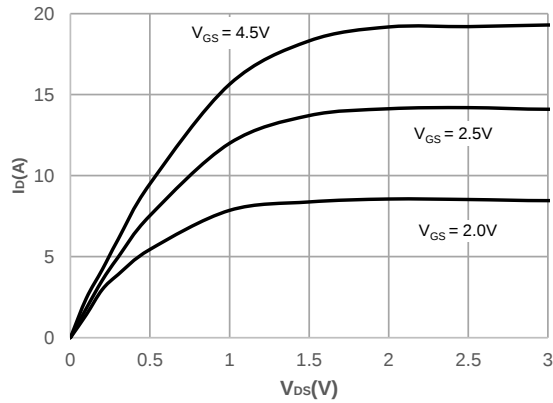


Figure 2: Typical Transfer Characteristics

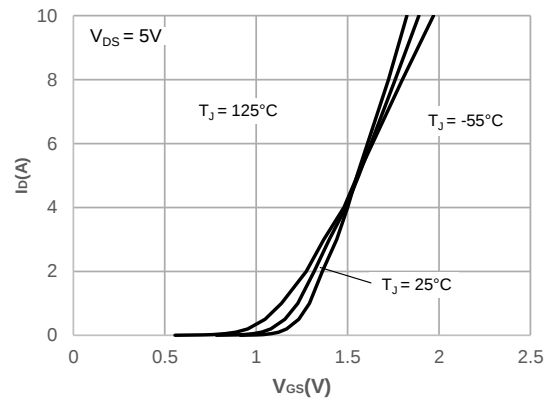


Figure 3: On-resistance vs. Drain Current

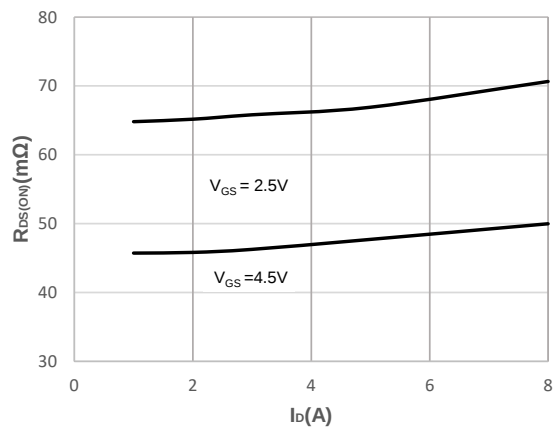


Figure 4: Body Diode Characteristics

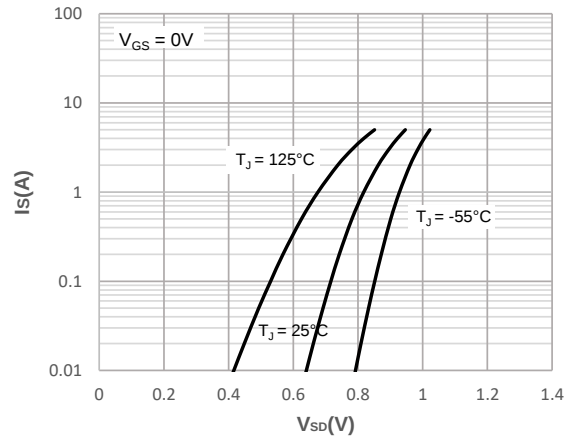


Figure 5: Gate Charge Characteristics

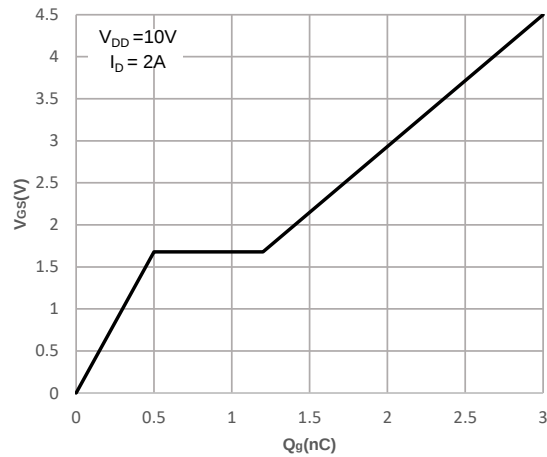
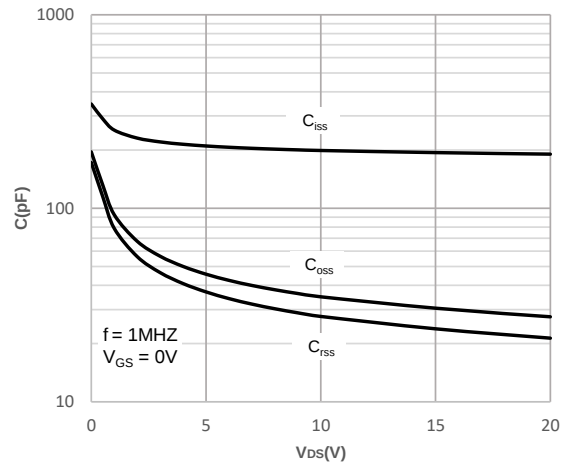


Figure 6: Capacitance Characteristics



RATING AND CHARACTERISTIC CURVES (DMG2302UK)

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

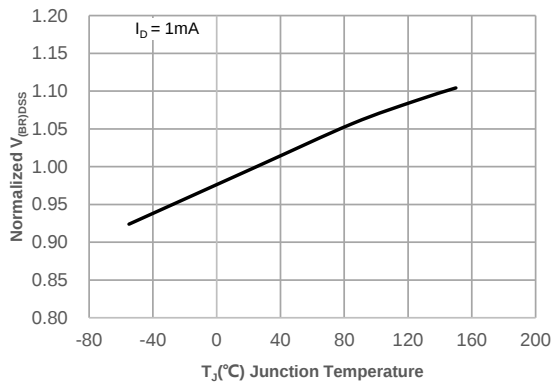


Figure 8: Normalized on Resistance vs. Junction Temperature

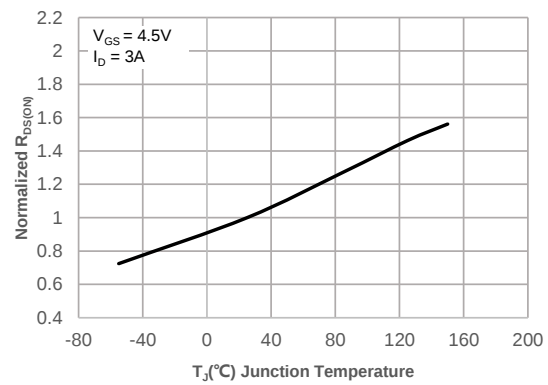


Figure 9: Maximum Safe Operating Area

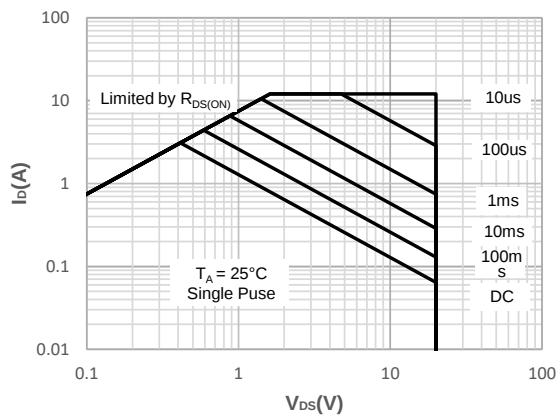


Figure 10: Maximum Continuous Driian Current vs. Ambient Temperature

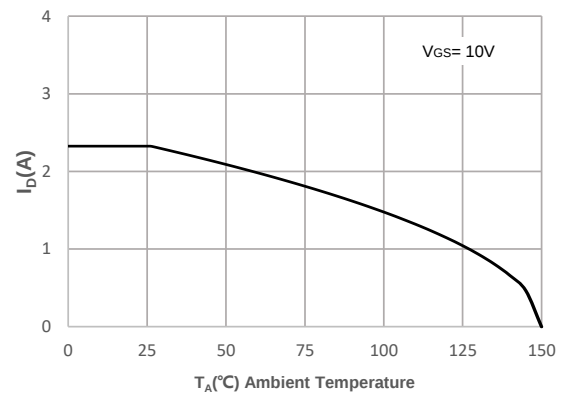


Figure 11: Normalized Maximum Transient Thermal Impedance

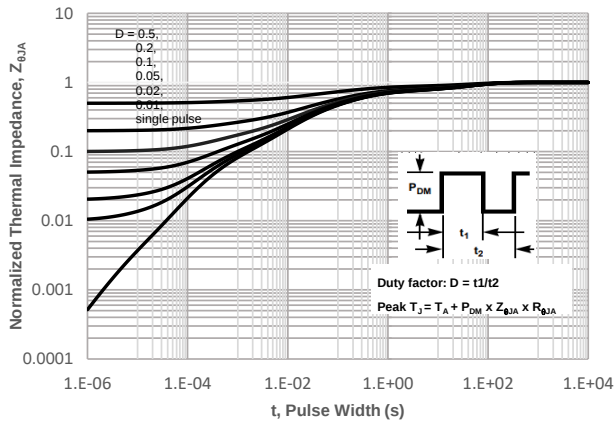
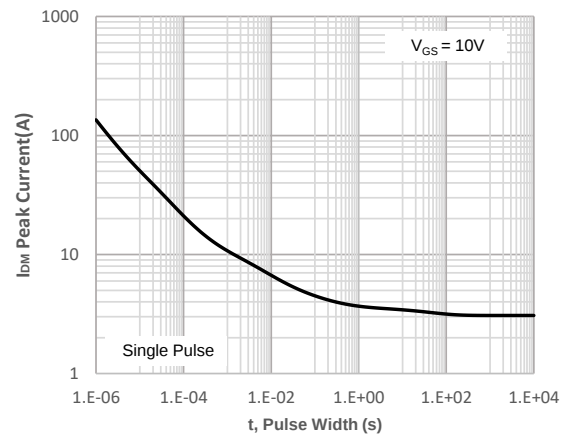


Figure 12: Peak Current Capacity



Test Circuit

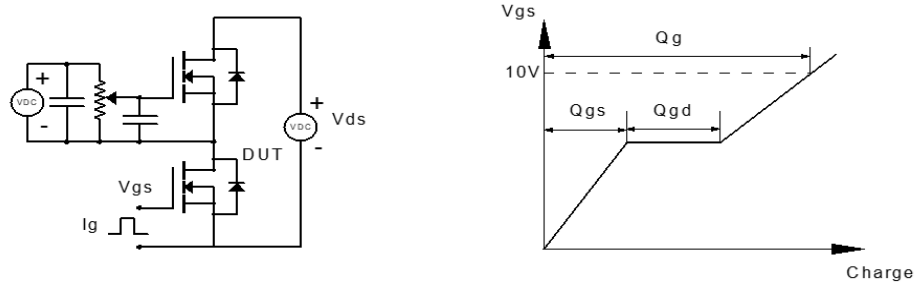


Figure 1: Gate Charge Test Circuit & Waveform

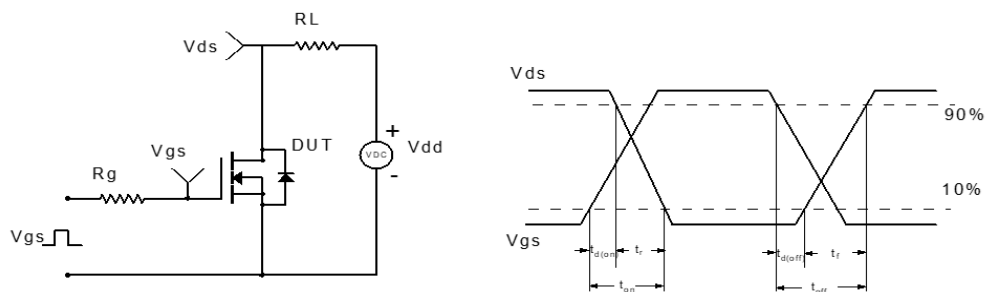


Figure 2: Resistive Switching Test Circuit & Waveform

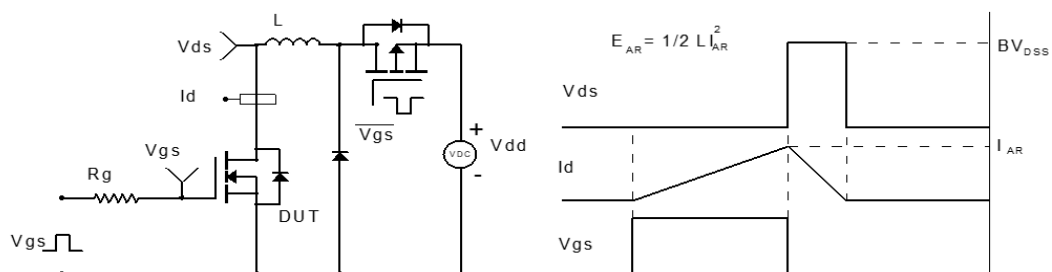


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

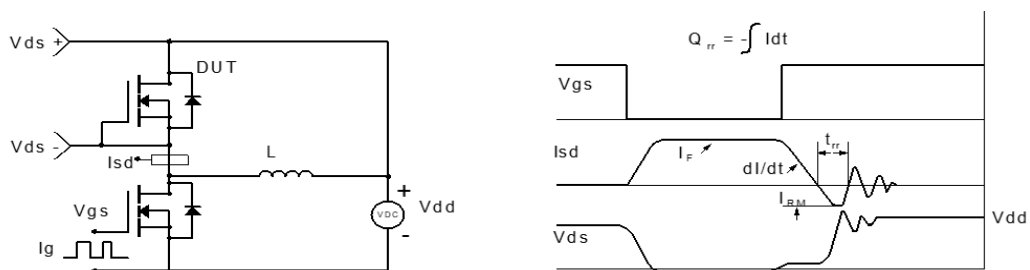


Figure 4: Diode Recovery Test Circuit & Waveform